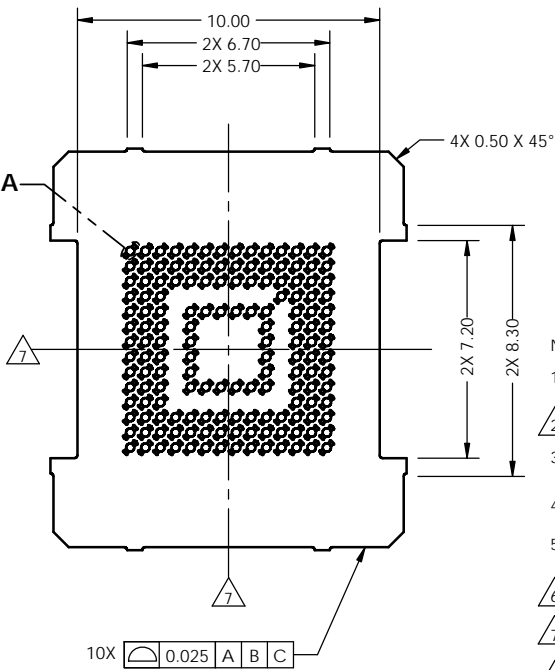
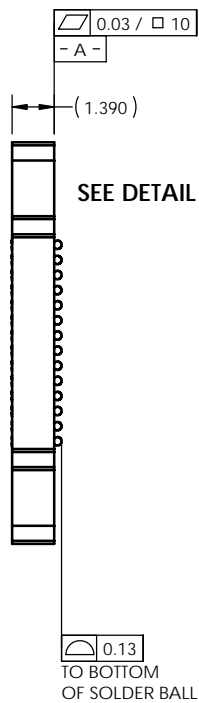
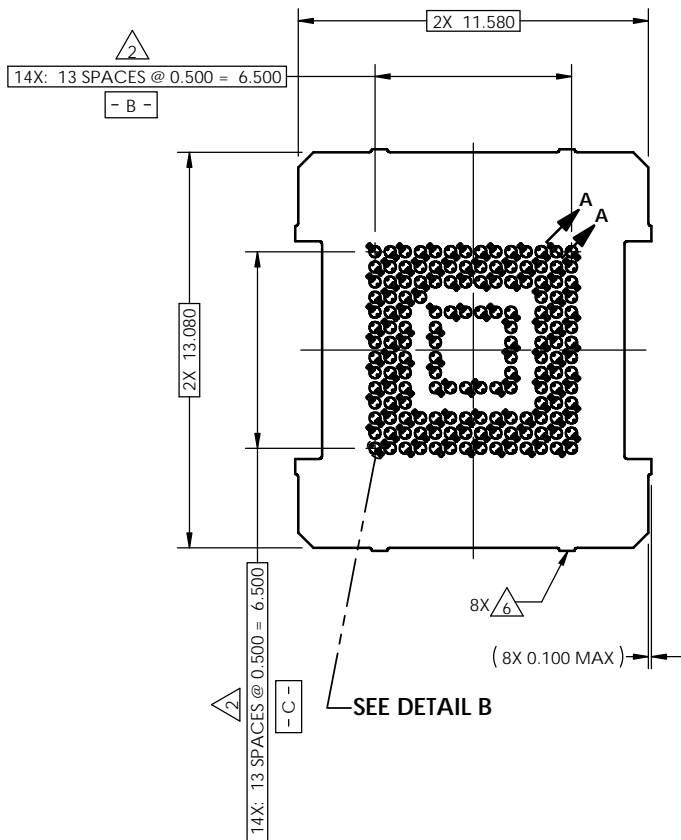


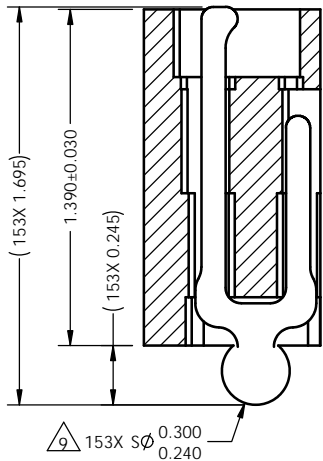
REV	ECO	BY	DESCRIPTION	APV	DATE
A	31309	MP	Initial Design	MP	06/14/13



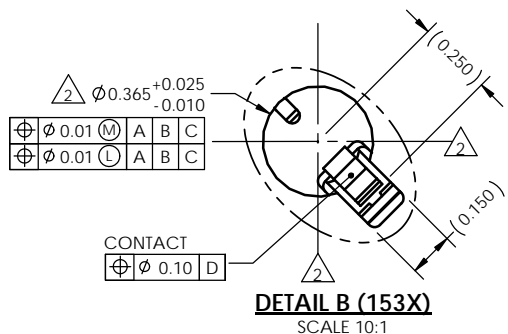
Notes:

- Reference HSIO Technologies specification 103862-0004 for solder attachment.
- Dimension locates center of contact/ slot.
- Reference HSIO Technologies specification 103863-0001 for application notes.
- Footprint part number is 104311-0291.
- Datums **- B -** and **- C -** are determined by $\phi 0.365$ features on corner slots.
- Tooling marks permitted. Maximum 0.10 protrusion (shown).
- E -** Center of ball pattern.
- F -** Center of contact.
- Eutectic solder balls.

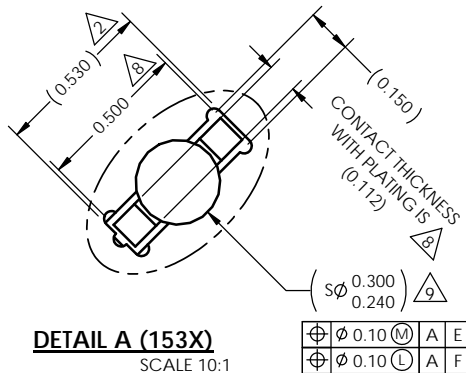
Parts List	
Part Number	Description
107248-0026	CS, 153G4011.5X13-0.50
103864-0128	PRESS, DEVICE INSERT, GRYP 11.5 X 13 (SOLD SEPARATELY)
105900-0004	EXTRACTION TOOL, 4 X 53 (SOLD SEPARATELY)
104553-0220	STEN FLEX, 153G4011.5X13-0.50 (SOLD SEPARATELY)



SECTION A-A
SCALE 8:1



DETAIL B (153X)
SCALE 10:1



DETAIL A (153X)
SCALE 10:1

HSIO technologies
PROPRIETARY AND CONFIDENTIAL

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UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES:
ANGULAR: ± 1°
XX ±0.25
XXX ±0.10
XXXX ±0.050

DRAWN	MP	06/14/13
CHECKED	MP	06/14/13

LEGEND:
 △ NOTE CALLOUT
 ○ REVISION CHANGE
 ○ ITEM NUMBER

NAME	DATE
MP	06/14/13

HSIO TECHNOLOGIES, LLC.
13300 67th AVENUE NORTH
MAPLE GROVE, MINNESOTA 55311
763-447-6260

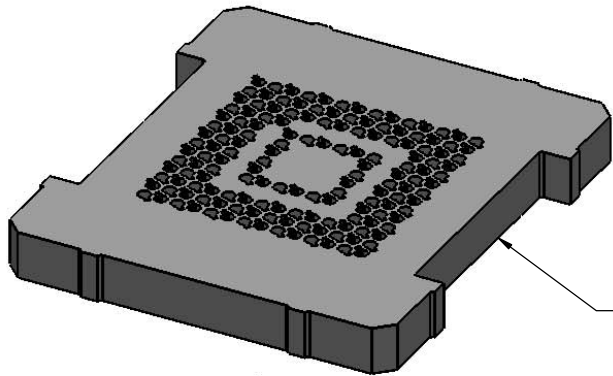
TITLE:
SKT, 153G4011.5X13-0.50
WITH EUTECTIC SOLDER BALLS

DWG. NO. **108387-0026** REV **A**

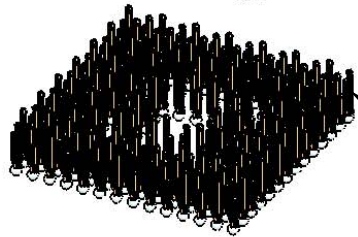
SCALE: 10:1 | SIZE: C | SHEET 1 OF 2

SOCKET FOR DEVICES THAT ARE WITHIN THESE SPECIFICATIONS					
Lead Count	N	153	Package Size	D	11.50
Columns	ND	14		E	13.00
Rows	NE	14	Ball Spacing	D1	13.500
Pitch	e	0.50		E1	13.500
Ball Size	b	0.30±0.05	Encapsulant/ Top Size	D2	n/a
Total Thickness	A	n/a		E2	n/a
Ball Height	A1	0.225 min.	Pattern Style	IRREGULAR*	
Substrate Thickness	A2	n/a	Perimeter Rows	3	
Top Thickness	A3		Center Array	n/a	
Form Tolerances					
Edge	aaa	0.10	Bottom	ddd	0.08
Substrate	bbb	0.10	Position	eee	0.15
top	ccc	0.10	Position	fff	0.05

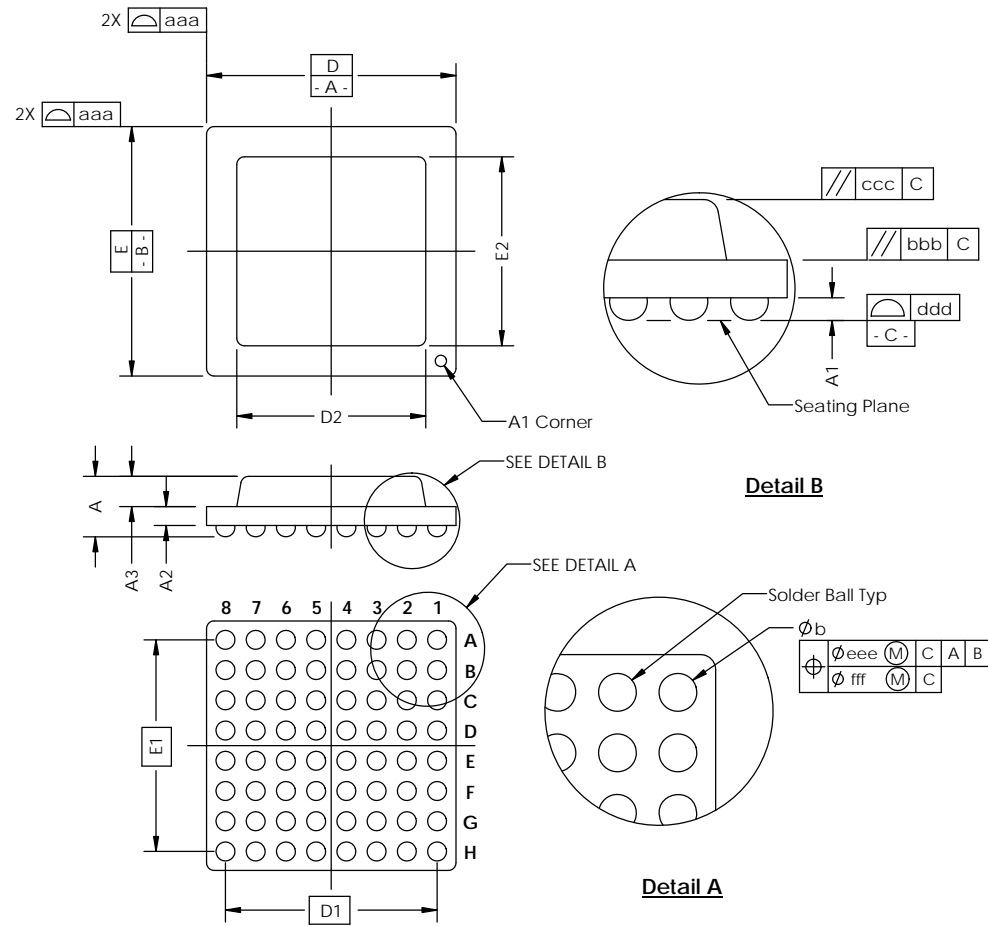
All dimensions are in millimeters.
* See footprint for pattern details.



HOUSING
107247-0026



153X CONTACT



Generic Representation with Full Grid Array

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UNLESS OTHERWISE SPECIFIED:	NAME	DATE	HSIO TECHNOLOGIES, LLC. 13300 67th AVENUE NORTH MAPLE GROVE, MINNESOTA 55311 763-447-6260
DIMENSIONS ARE IN MILLIMETERS	DRAWN	MP	
TOLERANCES: ANGULAR: ±1° X.X ±0.05 X.XX ±0.10 X.XXX ±0.050	CHECKED	MP	
LEGEND:			TITLE: SCKT, 153G4011.5X13-0.50 WITH EUTECTIC SOLDER BALLS
△ NOTE CALLOUT ○ REVISION CHANGE ○ ITEM NUMBER	DWG. NO. 108387-0026		REV A
SCALE: 5:1			SIZE: C SHEET 2 OF 2